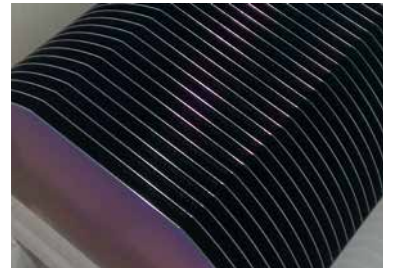
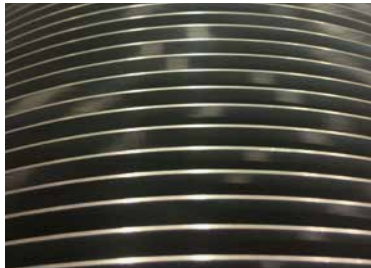
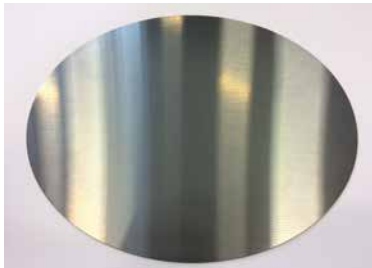


# DW 292-200

MULTI WIRE SAW



WORK PIECE DIMENSIONS:  
MAX. Ø 210 MM × 650 MM



## FLEXIBILITY FOR HIGH PRECISION 8" WAFER

- ✓ Slurry and Diamond Wire compatible
- ✓ High wire speed and acceleration
- ✓ Minimized deflection roller amount
- ✓ High process automation

SMART SLICING TECHNOLOGY FOR SEMICONDUCTOR WAFERING

## HIGHLIGHTS DW 292-200

- ✔ Slurry and Diamond Wire compatible
- ✔ Fast and easy change to Diamond Wire
- ✔ High throughput:  
35 m/s wire speed,  
12 m/s<sup>2</sup> acceleration
- ✔ 60 µm wire capability
- ✔ Perfect accessibility for daily operation
- ✔ Robust machine: Mineral cast, low temperature dependency, low vibration, low noise
- ✔ Shortest wire path in market: easy wire set-up and constant tension
- ✔ New HMI on 19" touch screen, production assistant, global process recipes, easy to train, easy to use
- ✔ Option: Automatic cutting fluid exchange
- ✔ Option: MES interface (SECS/GEM300)



Long load length for high output



Optimized axis distance for higher wafer quality



Easy operation for higher yield

TECHNICAL DATA	DW 292-200 FEATURES
Web length [mm]	660
Max. work piece dimensions [mm]	Ø 210 × 650
Wire speed [m/sec]	Slurry: 20 / DW: 35
Wire acceleration [m/s <sup>2</sup> ]	Slurry: 8 (< 3 s) / DW: 12 (< 3.5 s)
Min. wire diameter [µm]	60
Max. wire tension [N]	45
Deflection Roller [pcs]	6
Wire guide roller [pcs]	2
Cutting fluid tank [l]	300
Machine dimensions [L × W × H] [mm]	3800 × 1380 × 2860
Machine weight [kg]	10500

**GET IN TOUCH WITH US TODAY**  
**TOGETHER WE WILL FIND A SOLUTION**  
**FOR YOUR REQUIREMENTS**

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